

CUTTING APPARATUS

ABSTRACT OF THE DISCLOSURE

A cutting apparatus includes a cassette table on which a first cassette in which a frame unit, in which a ring-shaped frame and a wafer are integrated, is housed and a second cassette in which a simple wafer is housed are selectively placed, and a first conveying unit having a first frame holding part that holds the ring-shaped frame of the frame unit withdrawn from the first cassette and conveys the frame unit to a chuck table and a first wafer holding part that holds the simple wafer withdrawn from the second cassette and conveys the simple wafer to the chuck table. The cutting apparatus includes also a cutting unit that cuts the wafer held by the chuck table, and a second conveying unit having a second frame holding part that holds the ring-shaped frame of the cut frame unit and conveys the frame unit from the chuck table to a cleaning unit and a second wafer holding part that holds the cut simple wafer and conveys the simple wafer from the chuck table to the cleaning unit.

[Fig.1]